

DO NOT SCALE DRAWING

EC NO. DRAWN: CHK'g: APPR:	EC NO. DRAWN: CHK'g: APPR:	EC NO. DRAWN: CHK'g: APPR:	EC NO. DRAWN: CHK'g: APPR:	EC NO. DRAWN: CHK'g: APPR:	EC NO. J2004-3185 DRAWN: T.UENO CHK'g: M.SASAO APPR: M.SASAO	DESCRIPTION RELEASED '04/03/18	MATERIAL 材料	SEE NOTES	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE —	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	THIRD ANGLE PROJECTION	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY	SHT REVISE ON CAD ONLY
							FINISH 仕上り	SEE NOTES						
WIRE RANGE 適用電線範囲	—		ANGLE 角度	±3°		DRAWN BY & DATE T.UENO '04/03/18		CHECKED BY & DATE M.SASAO '04/03/18		APPROVED BY & DATE M.SASAO '04/03/18		TITLE: CF CARD CONN. 50P HEADER ASS'Y (NORMAL TYPE) -LEAD FREE-		
INS. RANGE 被覆外径	—		CAD FILENAME SD-55244-009.S01		MATERIAL NO. 55244-5029		DRAWING NO. SD-55244-009		SHEET NO. 1 OF 2		MOLEX INCORPORATED		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	

55244-5029
MODEL No.

DWG. NO. SD-55244-009

DO NOT SCALE DRAWING

注) NOTES

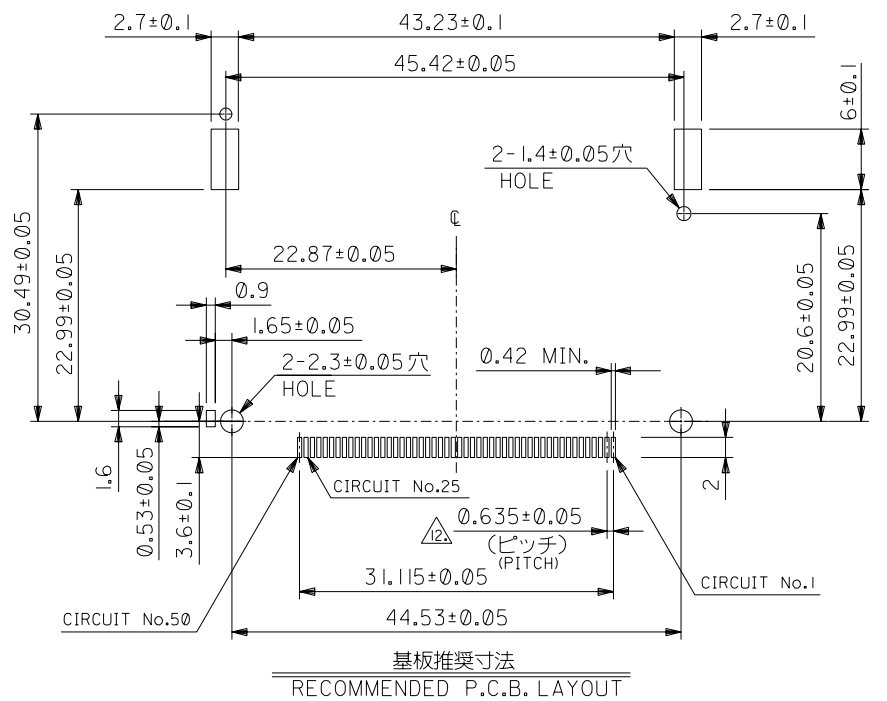
1. 材質 MATERIAL
 ハウジング : ガラス入り耐熱樹脂 UL94V-0
 HOUSING : LIQUID CRYSTAL POLYMER GLASS FILLED UL94V-0
 ピン : リン青銅
 PIN : PHOSPHOR BRONZE
 ネール : リン青銅
 NAIL : PHOSPHOR BRONZE

2. メッキ仕様 PLATING

PIN	接点部 CONTACT AREA	金めっき GOLD PLATING
		パラジウムニッケルめっき PALLADIUM-NICKEL PLATING
	半田付け部 SOLDER TAIL AREA	錫めっき TIN PLATING
	下地めっき UNDERPLATING	ニッケルめっき NICKEL PLATING
NAIL	接点部 CONTACT AREA	金めっき GOLD PLATING
	半田付け部 SOLDER TAIL AREA	錫めっき TIN PLATING
	下地めっき UNDERPLATING	ニッケルめっき NICKEL PLATING

3. 推奨基板厚 : $t \pm 0.8$ MIN.
 RECOMMENDED P.C.B. THICKNESS: $t \pm 0.8$ MIN.
 4. 適合カード厚 : 3.3 ± 0.1 (TYPE I) AND 5 MAX. (TYPE II)
 RECOMMENDED CARD THICKNESS: 3.3 ± 0.1 (TYPE I) AND 5 MAX. (TYPE II)
 5. 適合カード幅 : 42.8 ± 0.1
 RECOMMENDED CARD WIDTH: 42.8 ± 0.1
 6. ハウジング色 : 黒
 HOUSING COLOR: BLACK

△1. 寸法適用極 : 1,13,38,50
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 1,13,38 AND 50.
 △2. 寸法適用極 : 25,26
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.
 △3. ピンの倒れは、ピン根元を基準に全方向へ 0.1 MAX.とする。
 PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1 WHEN MEASURED FROM PIN BASE.
 △10. ピン根元に適用する。
 THIS DIMENSION TO BE MEASURED AT PIN BASE.
 △11. ソルダータール及びネールは、Z面を基準とし上へ 0.05 下へ 0.15 の範囲にあり、且つソルダータールの平坦度は、 0.12 MAX. とし、テール先端にて測定する。
 SOLDER TAILS AND FITTING NAILS TO BE WITHIN 0.05 UPWARD AND 0.15 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF SOLDER TAILS TO BE WITHIN 0.12 . MEASUREMENT POINT IS SOLDER TAILS TIP.



- △12. 公差非累積 NON-CUMULATIVE
- △13. テールとネールを併せた平坦度は、 0.12 MAX.とする。
 TOTAL COPLANARITY OF SOLDER TAILS AND FITTING NAILS TO BE 0.12 MAX.
- △14. ボタンストロークが (6 mm) の時、カード飛び出し量は (3.25mm)。
 WHEN BUTTON PUSH STROKE IS (6mm), CARD OUT BY (3.25mm).
- 15. 適合 SHELL ASS'Y : 55246-001* , 58773-0010
 APPLICABLE SHELL ASS'Y : 55246-001* , 58773-0010
- 16. 本製品は 55244-5021 の鉛フリー品である。
 THIS PRODUCT IS LEAD FREE OF 55244-5021.

EC NO. DRWNS: CH'K: APPR:					SEE SHEET 1 OF 2	MATERIAL 材料		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY	SHT	REV
EC NO. DRWNS: CH'K: APPR:						SEE SHEET 1 OF 2	SEE NOTES		10 UNDER 未満	±0.2	DRAWN BY & DATE T.UENO '04/03/18	TITLE: CF CARD CONN. 50P HEADER ASS'Y (NORMAL TYPE) -LEAD FREE-	MATERIAL NO. 55244-5029	DRAWING NO. SD-55244-009	SHEET NO. 2
EC NO. DRWNS: CH'K: APPR:							SEE SHEET 1 OF 2	SEE NOTES		10 OVER 30 UNDER 未満	±0.25				
EC NO. DRWNS: CH'K: APPR:								REV	INS. RANGE 被覆外径		30 OVER 以上	±0.3	APPROVED BY & DATE M.SASAO '04/03/18	MOLEX INCORPORATED	
EC NO. DRWNS: CH'K: APPR:					0	—		ANGLE 角度	±3°	CAD FILENAME SD-55244-009.S02		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.			